## Abstract

The invention provides a method for encasing an electronic component, in particular an integrated circuit, with a hardening plastic, in which the component is placed in the cavity of a splittable mould, and prior to the injection of material into said cavity a film which is detachable from the walls of the cavity is placed between the component and said walls, and the plastic is injected into the space between the component and the film, in which use is made of a film which at the side facing the component bears a material which adheres better to the still warm injected plastic encasing the component than to the film, and thus remains adhering to the plastic encasement when the latter is removed from the mould after cooling.


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